3DS-IC North America TC Chapter

SEMICON West 2017 Standards Meetings

Wednesday, July 12

Marriott Marquis Hotel, San Francisco, CA

15:00–17:00

AGENDA

1 Welcome/Call to Order

1.1 Introductions

1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Liaison Report

3.1 Japan TC Chapter

3.2 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

5.1 Document 5822A — New Standard, Specification for Reference Material for Bonded Wafer Stack Void Metrology

5.2 Document 6179 — Reapproval of SEMI 3D1-0912, Terminology for Through Silicon via Geometrical Metrology

6 Task Force Reports

6.1 Bonded Wafer Stacks

6.2 Inspection & Metrology

7 Old Business

7.1 Standards due for Five-Year Review

8 New Business

8.1 Panel Scale Fan Out Discussion – Rich Allen / Cristina Chu (TEL)

8.2 TEM Grid Survey Presentation – Troy Morrison (Thermo Fisher Scientific)

8.3 3DS-IC Charter Proposal Update – Junko Collins (SEMI Japan)

8.4 New TFOF(s) and SNARF(s)

8.5 Upcoming Ballot(s)

9 Action Item Review

9.1 Open Action Items

Item #	*Assigned to*	*Details*
2017April#03	Rich Allen	To contact Victor Vartanian and David Read to see if they are still interesting of being TF leader.
2017April#02	Junko Collins	To set up recurring meetings between NA and Japan every two weeks to discuss the details of the charter proposal and potentially have a final proposal to present at SEMICON West. CLOSED.

9.2 New Action Items

10 Next Meeting and Adjournment

10.1 The next meeting is scheduled for November 8, 2017 at SEMI Headquarters in Milpitas, California.

(Tentative)
Wednesday, November 8
13:00-14:00 3DS-IC Inspection and Metrology (TF)
14:00-15:00 3DS-IC Bonded Wafer Stacks (TF)
15:00-17:00 3DS-IC (C)

2017/06/16
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